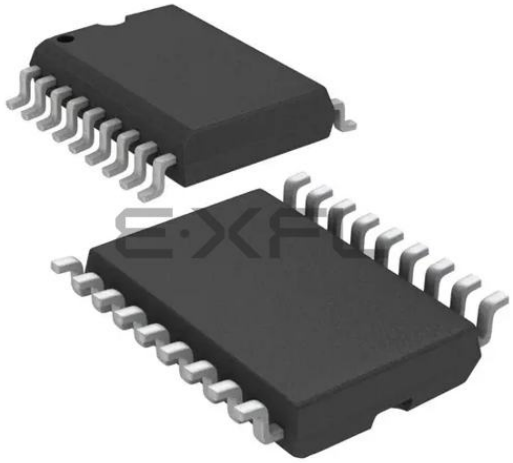


Welcome to E-XFL.COM

What is "Embedded - Microcontrollers"?

"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	PIC
Core Size	8-Bit
Speed	20MHz
Connectivity	I²C, SPI
Peripherals	Brown-out Detect/Reset, POR, PWM, WDT
Number of I/O	16
Program Memory Size	3.5KB (2K x 14)
Program Memory Type	FLASH
EEPROM Size	256 x 8
RAM Size	256 x 8
Voltage - Supply (Vcc/Vdd)	4V ~ 5.5V
Data Converters	A/D 5x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	18-SOIC (0.295", 7.50mm Width)
Supplier Device Package	18-SOIC
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic16f819t-i-so

2.2.2.6 PIE2 Register

The PIE2 register contains the individual enable bit for the EEPROM write operation interrupt.

REGISTER 2-6: PIE2: PERIPHERAL INTERRUPT ENABLE REGISTER 2 (ADDRESS 8Dh)

U-0	U-0	U-0	R/W-0	U-0	U-0	U-0	U-0
—	—	—	EEIE	—	—	—	—
bit 7							bit 0

bit 7-5 **Unimplemented:** Read as '0'

bit 4 **EEIE**: EEPROM Write Operation Interrupt Enable bit
1 = Enable EE write interrupt
0 = Disable EE write interrupt

bit 3-0 **Unimplemented:** Read as '0'

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

2.2.2.7 PIR2 Register

The PIR2 register contains the flag bit for the EEPROM write operation interrupt.

Note: Interrupt flag bits are set when an interrupt condition occurs regardless of the state of its corresponding enable bit or the Global Interrupt Enable bit, GIE (INTCON<7>). User software should ensure the appropriate interrupt flag bits are clear prior to enabling an interrupt.

REGISTER 2-7: PIR2: PERIPHERAL INTERRUPT REQUEST (FLAG) REGISTER 2 (ADDRESS 0Dh)

U-0	U-0	U-0	R/W-0	U-0	U-0	U-0	U-0
—	—	—	EEIF	—	—	—	—
bit 7							bit 0

bit 7-5 **Unimplemented:** Read as '0'

bit 4 **EEIF**: EEPROM Write Operation Interrupt Enable bit
1 = Enable EE write interrupt
0 = Disable EE write interrupt

bit 3-0 **Unimplemented:** Read as '0'

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

An example of the complete four-word write sequence is shown in Example 3-5. The initial address is loaded into the EEADRH:EEADR register pair; the four words of data are loaded using indirect addressing, assuming that a row erase sequence has already been performed.

EXAMPLE 3-5: WRITING TO FLASH PROGRAM MEMORY

```
; This write routine assumes the following:

; 1. The 32 words in the erase block have already been erased.
; 2. A valid starting address (the least significant bits = '00') is loaded into EEADRH:EEADR
; 3. This example is starting at 0x100, this is an application dependent setting.
; 4. The 8 bytes (4 words) of data are loaded, starting at an address in RAM called ARRAY.
; 5. This is an example only, location of data to program is application dependent.
; 6. word_block is located in data memory.

        BANKSEL  EECON1            ;prepare for WRITE procedure
        BSF      EECON1, EEPGD     ;point to program memory
        BSF      EECON1, WREN      ;allow write cycles
        BCF      EECON1, FREE      ;perform write only

        BANKSEL  word_block
        MOVLW    .4
        MOVWF    word_block        ;prepare for 4 words to be written

        BANKSEL  EEADRH            ;Start writing at 0x100
        MOVLW    0x01
        MOVWF    EEADRH            ;load HIGH address
        MOVLW    0x00
        MOVWF    EEADR             ;load LOW address
        BANKSEL  ARRAY
        MOVLW    ARRAY             ;initialize FSR to start of data
        MOVWF    FSR
LOOP
        BANKSEL  EEDATA
        MOVF     INDF, W           ;indirectly load EEDATA
        MOVWF    EEDATA
        INCF     FSR, F            ;increment data pointer
        MOVF     INDF, W           ;indirectly load EEDATH
        MOVWF    EEDATH
        INCF     FSR, F            ;increment data pointer

        BANKSEL  EECON1
        MOVLW    0x55              ;required sequence
        MOVWF    EECON2
        MOVLW    0xAA
        MOVWF    EECON2
        BSF      EECON1, WR        ;set WR bit to begin write
        NOP                        ;instructions here are ignored as processor
        NOP

        BANKSEL  EEADR
        INCF     EEADR, f          ;load next word address
        BANKSEL  word_block
        DECFSZ   word_block, f     ;have 4 words been written?
        GOTO     loop              ;NO, continue with writing

        BANKSEL  EECON1
        BCF      EECON1, WREN      ;YES, 4 words complete, disable writes
        BSF      INTCON, GIE       ;enable interrupts
```

Required Sequence

3.8 Protection Against Spurious Write

There are conditions when the device should not write to the data EEPROM memory. To protect against spurious EEPROM writes, various mechanisms have been built-in. On power-up, WREN is cleared. Also, the Power-up Timer (72 ms duration) prevents an EEPROM write.

The write initiate sequence and the WREN bit together help prevent an accidental write during brown-out, power glitch or software malfunction.

3.9 Operation During Code-Protect

When the data EEPROM is code-protected, the microcontroller can read and write to the EEPROM normally. However, all external access to the EEPROM is disabled. External write access to the program memory is also disabled.

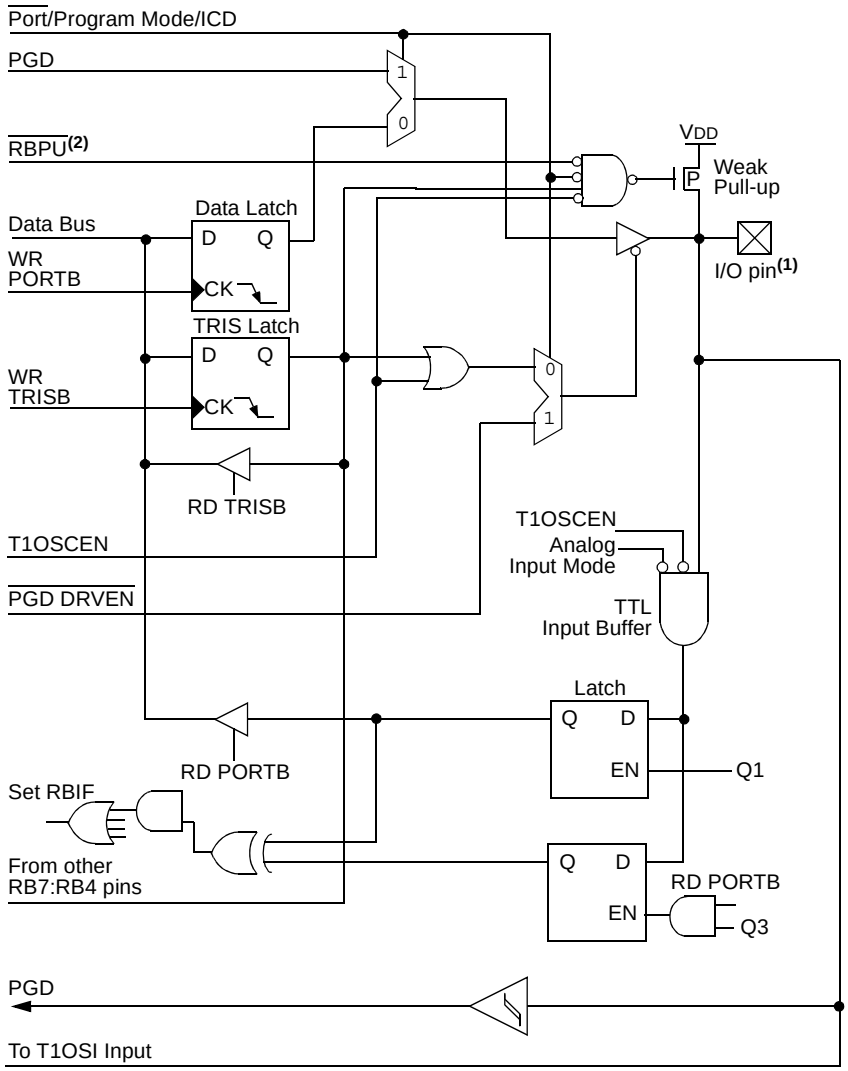
When program memory is code-protected, the microcontroller can read and write to program memory normally as well as execute instructions. Writes by the device may be selectively inhibited to regions of the memory depending on the setting of bits, WRT1:WRT0, of the Configuration Word (see **Section 12.1 "Configuration Bits"** for additional information). External access to the memory is also disabled.

TABLE 3-1: REGISTERS/BITS ASSOCIATED WITH DATA EEPROM AND FLASH PROGRAM MEMORIES

Address	Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Value on Power-on Reset	Value on all other Resets
10Ch	EEDATA	EEPROM/Flash Data Register Low Byte								xxxx xxxx	uuuu uuuu
10Dh	EEADR	EEPROM/Flash Address Register Low Byte								xxxx xxxx	uuuu uuuu
10Eh	EEDATH	—	—	EEPROM/Flash Data Register High Byte						--xx xxxx	--uu uuuu
10Fh	EEADRH	—	—	—	—	—	EEPROM/Flash Address Register High Byte			---- -xxx	---- -uuu
18Ch	EECON1	EEPGD	—	—	FREE	WRERR	WREN	WR	RD	x--x x000	x--x q000
18Dh	EECON2	EEPROM Control Register 2 (not a physical register)								---- ----	---- ----
0Dh	PIR2	—	—	—	EEIF	—	—	—	—	---0 ----	---0 ----
8Dh	PIE2	—	—	—	EEIE	—	—	—	—	---0 ----	---0 ----

Legend: x = unknown, u = unchanged, - = unimplemented, read as '0', q = value depends upon condition.
Shaded cells are not used by data EEPROM or Flash program memory.

FIGURE 5-15: BLOCK DIAGRAM OF RB7 PIN



Note 1: I/O pins have diode protection to VDD and VSS.
2: To enable weak pull-ups, set the appropriate TRIS bit(s) and clear the RBPU bit.

EXAMPLE 6-1: CHANGING THE PRESCALER ASSIGNMENT FROM TIMER0 TO WDT

```
    BANKSEL  OPTION_REG     ; Select Bank of OPTION_REG
    MOVLW    b'xx0x0xxx'    ; Select clock source and prescale value of
    MOVWF    OPTION_REG     ; other than 1:1
    BANKSEL  TMR0           ; Select Bank of TMR0
    CLRF     TMR0           ; Clear TMR0 and prescaler
    BANKSEL  OPTION_REG     ; Select Bank of OPTION_REG
    MOVLW    b'xxxx1xxx'    ; Select WDT, do not change prescale value
    MOVWF    OPTION_REG
    CLRWDT                  ; Clears WDT and prescaler
    MOVLW    b'xxxx1xxx'    ; Select new prescale value and WDT
    MOVWF    OPTION_REG
```

EXAMPLE 6-2: CHANGING THE PRESCALER ASSIGNMENT FROM WDT TO TIMER0

```
CLRWDT                  ; Clear WDT and prescaler
BANKSEL  OPTION_REG     ; Select Bank of OPTION_REG
MOVLW    b'xxxx0xxx'    ; Select TMR0, new prescale
MOVWF    OPTION_REG     ; value and clock source
```

TABLE 6-1: REGISTERS ASSOCIATED WITH TIMER0

Address	Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Value on POR, BOR	Value on all other Resets
01h,101h	TMR0	Timer0 Module Register								xxxx xxxx	uuuu uuuu
0Bh,8Bh, 10Bh,18Bh	INTCON	GIE	PEIE	TMR0IE	INTE	RBIE	TMR0IF	INTF	RBIF	0000 000x	0000 000u
81h,181h	OPTION_REG	$\overline{\text{RBPU}}$	INTEDG	T0CS	T0SE	PSA	PS2	PS1	PS0	1111 1111	1111 1111

Legend: x = unknown, u = unchanged, - = unimplemented locations read as '0'. Shaded cells are not used by Timer0.

7.6 Timer1 Oscillator

A crystal oscillator circuit is built-in between pins T1OSI (input) and T1OSO (amplifier output). It is enabled by setting control bit, T1OSCEN (T1CON<3>). The oscillator is a low-power oscillator, rated up to 32.768 kHz. It will continue to run during Sleep. It is primarily intended for a 32 kHz crystal. The circuit for a typical LP oscillator is shown in Figure 7-3. Table 7-1 shows the capacitor selection for the Timer1 oscillator.

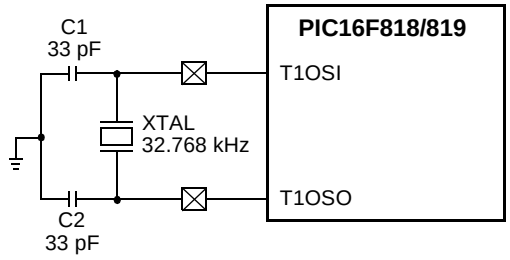
The user must provide a software time delay to ensure proper oscillator start-up.

Note: The Timer1 oscillator shares the T1OSI and T1OSO pins with the PGD and PGC pins used for programming and debugging.

When using the Timer1 oscillator, In-Circuit Serial Programming™ (ICSP™) may not function correctly (high-voltage or low-voltage) or the In-Circuit Debugger (ICD) may not communicate with the controller. As a result of using either ICSP or ICD, the Timer1 crystal may be damaged.

If ICSP or ICD operations are required, the crystal should be disconnected from the circuit (disconnect either lead) or installed after programming. The oscillator loading capacitors may remain in-circuit during ICSP or ICD operation.

FIGURE 7-3: EXTERNAL COMPONENTS FOR THE TIMER1 LP OSCILLATOR



Note: See the Notes with Table 7-1 for additional information about capacitor selection.

TABLE 7-1: CAPACITOR SELECTION FOR THE TIMER1 OSCILLATOR

Osc Type	Freq	C1	C2
LP	32 kHz	33 pF	33 pF

Note 1: Microchip suggests this value as a starting point in validating the oscillator circuit.

2: Higher capacitance increases the stability of the oscillator but also increases the start-up time.

3: Since each resonator/crystal has its own characteristics, the user should consult the resonator/crystal manufacturer for appropriate values of external components.

4: Capacitor values are for design guidance only.

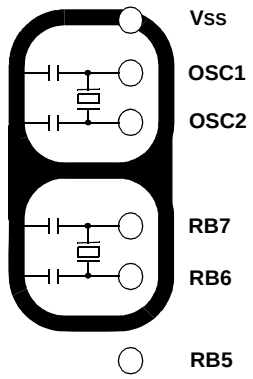
7.7 Timer1 Oscillator Layout Considerations

The Timer1 oscillator circuit draws very little power during operation. Due to the low-power nature of the oscillator, it may also be sensitive to rapidly changing signals in close proximity.

The oscillator circuit, shown in Figure 7-3, should be located as close as possible to the microcontroller. There should be no circuits passing within the oscillator circuit boundaries other than VSS or VDD.

If a high-speed circuit must be located near the oscillator, a grounded guard ring around the oscillator circuit, as shown in Figure 7-4, may be helpful when used on a single-sided PCB or in addition to a ground plane.

FIGURE 7-4: OSCILLATOR CIRCUIT WITH GROUNDED GUARD RING



The ADRESH:ADRESL registers contain the result of the A/D conversion. When the A/D conversion is complete, the result is loaded into the A/D Result register pair, the GO/DONE bit (ADCON0<2>) is cleared and A/D Interrupt Flag bit, ADIF, is set. The block diagram of the A/D module is shown in Figure 11-1.

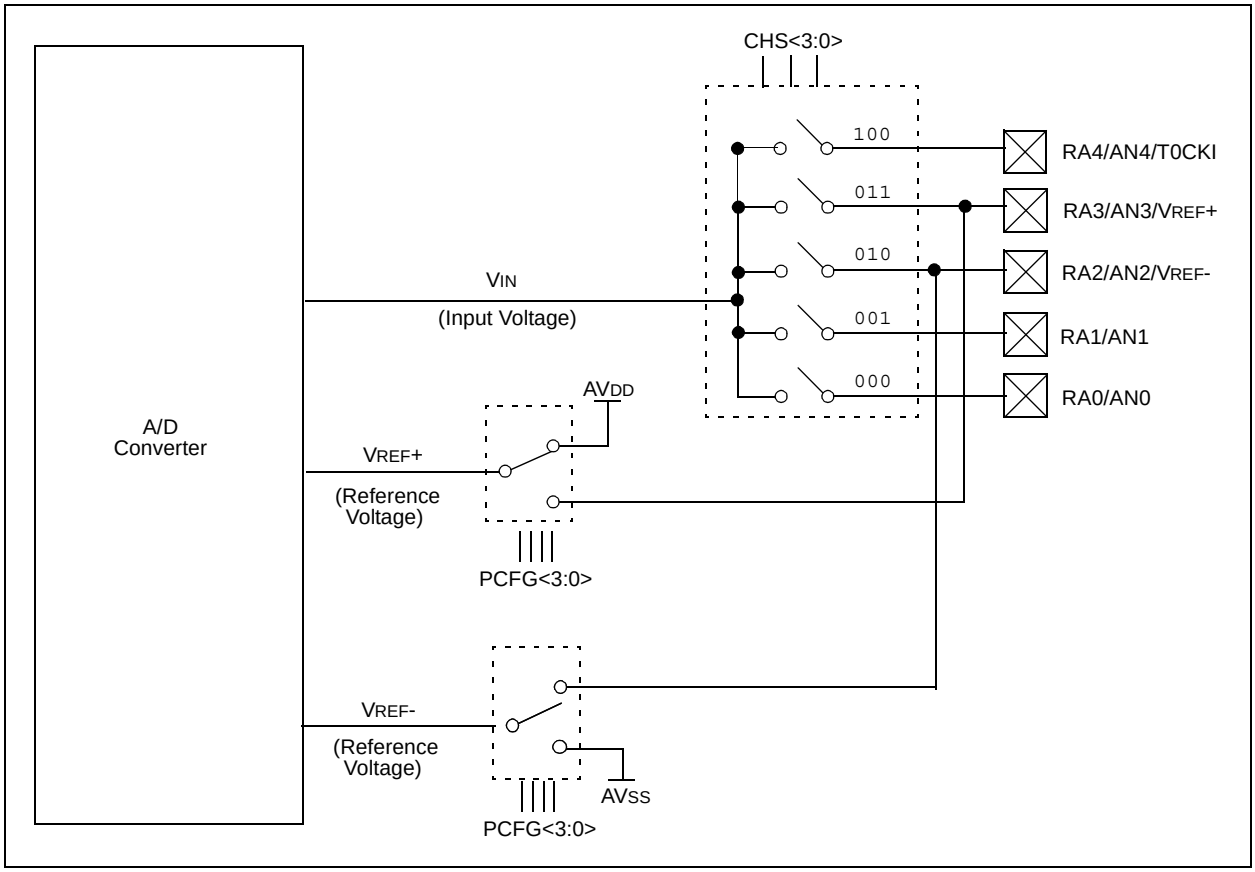
After the A/D module has been configured as desired, the selected channel must be acquired before the conversion is started. The analog input channels must have their corresponding TRIS bits selected as inputs.

To determine sample time, see **Section 11.1 "A/D Acquisition Requirements"**. After this sample time has elapsed, the A/D conversion can be started.

These steps should be followed for doing an A/D conversion:

1. Configure the A/D module:
   - Configure analog pins/voltage reference and digital I/O (ADCON1)
   - Select A/D input channel (ADCON0)
   - Select A/D conversion clock (ADCON0)
   - Turn on A/D module (ADCON0)
2. Configure A/D interrupt (if desired):
   - Clear ADIF bit
   - Set ADIE bit
   - Set GIE bit
3. Wait the required acquisition time.
4. Start conversion:
   - Set GO/DONE bit (ADCON0)
5. Wait for A/D conversion to complete by either:
   - Polling for the GO/DONE bit to be cleared (with interrupts disabled); OR
   - Waiting for the A/D interrupt
6. Read A/D Result register pair (ADRESH:ADRESL), clear bit ADIF if required.
7. For next conversion, go to step 1 or step 2 as required. The A/D conversion time per bit is defined as TAD. A minimum wait of 2 TAD is required before the next acquisition starts.

FIGURE 11-1: A/D BLOCK DIAGRAM



12.3 MCLR

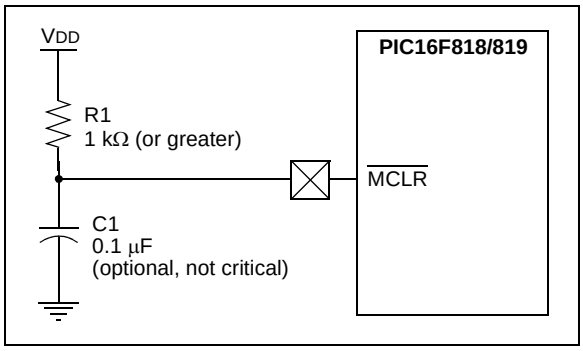
PIC16F818/819 device has a noise filter in the MCLR Reset path. The filter will detect and ignore small pulses.

It should be noted that a WDT Reset does not drive MCLR pin low.

The behavior of the ESD protection on the MCLR pin has been altered from previous devices of this family. Voltages applied to the pin that exceed its specification can result in both MCLR and excessive current beyond the device specification during the ESD event. For this reason, Microchip recommends that the MCLR pin no longer be tied directly to VDD. The use of an RC network, as shown in Figure 12-2, is suggested.

The RA5/MCLR/VPP pin can be configured for MCLR (default) or as an I/O pin (RA5). This is configured through the MCLRE bit in the Configuration Word register.

FIGURE 12-2: RECOMMENDED MCLR CIRCUIT



12.4 Power-on Reset (POR)

A Power-on Reset pulse is generated on-chip when VDD rise is detected (in the range of 1.2V-1.7V). To take advantage of the POR, tie the MCLR pin to VDD as described in **Section 12.3 "MCLR**". A maximum rise time for VDD is specified. See **Section 15.0 "Electrical Characteristics"** for details.

When the device starts normal operation (exits the Reset condition), device operating parameters (voltage, frequency, temperature, ...) must be met to ensure operation. If these conditions are not met, the device must be held in Reset until the operating conditions are met. For more information, see Application Note *AN607, "Power-up Trouble Shooting"* (DS00607).

12.5 Power-up Timer (PWRT)

The Power-up Timer (PWRT) of the PIC16F818/819 is a counter that uses the INTRC oscillator as the clock input. This yields a count of 72 ms. While the PWRT is counting, the device is held in Reset.

The power-up time delay depends on the INTRC and will vary from chip-to-chip due to temperature and process variation. See DC parameter #33 for details.

The PWRT is enabled by clearing configuration bit, PWRTEN.

12.6 Oscillator Start-up Timer (OST)

The Oscillator Start-up Timer (OST) provides 1024 oscillator cycles (from OSC1 input) delay after the PWRT delay is over (if enabled). This helps to ensure that the crystal oscillator or resonator has started and stabilized.

The OST time-out is invoked only for XT, LP and HS modes and only on Power-on Reset or wake-up from Sleep.

12.7 Brown-out Reset (BOR)

The configuration bit, BOREN, can enable or disable the Brown-out Reset circuit. If VDD falls below VBOR (parameter #D005, about 4V) for longer than TBOR (parameter #35, about 100 μs), the brown-out situation will reset the device. If VDD falls below VBOR for less than TBOR, a Reset may not occur.

Once the brown-out occurs, the device will remain in Brown-out Reset until VDD rises above VBOR. The Power-up Timer (if enabled) will keep the device in Reset for TPWRT (parameter #33, about 72 ms). If VDD should fall below VBOR during TPWRT, the Brown-out Reset process will restart when VDD rises above VBOR with the Power-up Timer Reset. Unlike previous PIC16 devices, the PWRT is no longer automatically enabled when the Brown-out Reset circuit is enabled. The PWRTEN and BOREN configuration bits are independent of each other.

12.8 Time-out Sequence

On power-up, the time-out sequence is as follows: the PWRT delay starts (if enabled) when a POR occurs. Then, OST starts counting 1024 oscillator cycles when PWRT ends (LP, XT, HS). When the OST ends, the device comes out of Reset.

If MCLR is kept low long enough, all delays will expire. Bringing MCLR high will begin execution immediately. This is useful for testing purposes or to synchronize more than one PIC16F818/819 device operating in parallel.

Table 12-3 shows the Reset conditions for the Status, PCON and PC registers, while Table 12-4 shows the Reset conditions for all the registers.

12.12 Watchdog Timer (WDT)

For PIC16F818/819 devices, the WDT is driven by the INTRC oscillator. When the WDT is enabled, the INTRC (31.25 kHz) oscillator is enabled. The nominal WDT period is 16 ms and has the same accuracy as the INTRC oscillator.

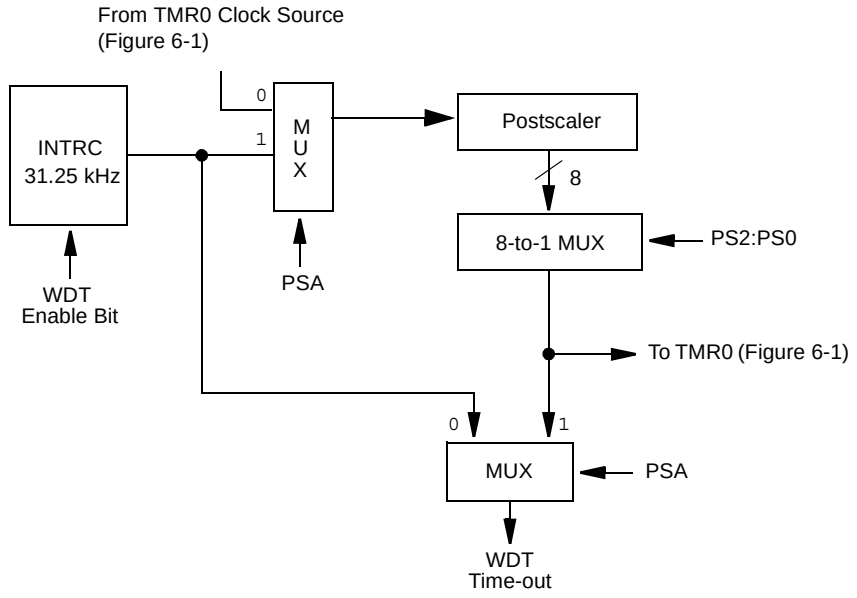
During normal operation, a WDT time-out generates a device Reset (Watchdog Timer Reset). If the device is in Sleep mode, a WDT time-out causes the device to wake-up and continue with normal operation (Watchdog Timer wake-up). The $\overline{TO}$ bit in the Status register will be cleared upon a Watchdog Timer time-out.

The WDT can be permanently disabled by clearing configuration bit, WDTEN (see **Section 12.1 "Configuration Bits"**).

WDT time-out period values may be found in **Section 15.0 "Electrical Characteristics"** under parameter #31. Values for the WDT prescaler (actually a postscaler but shared with the Timer0 prescaler) may be assigned using the OPTION_REG register.

Note 1:	The `CLRWDT` and `SLEEP` instructions clear the WDT and the postscaler if assigned to the WDT and prevent it from timing out and generating a device Reset condition.
2:	When a `CLRWDT` instruction is executed and the prescaler is assigned to the WDT, the prescaler count will be cleared but the prescaler assignment is not changed.

FIGURE 12-8: WATCHDOG TIMER BLOCK DIAGRAM



Note: PSA and PS2:PS0 are bits in the OPTION_REG register.

TABLE 12-5: SUMMARY OF WATCHDOG TIMER REGISTERS

Address	Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0
81h,181h	OPTION_REG	$\overline{RBPU}$	INTEDG	T0CS	T0SE	PSA	PS2	PS1	PS0
2007h	Configuration bits(1)	LVP	BOREN	MCLRE	FOSC2	$\overline{PWRTEN}$	WDTEN	FOSC1	FOSC0

Legend: Shaded cells are not used by the Watchdog Timer.

Note 1: See Register 12-1 for operation of these bits.

FIGURE 15-1: PIC16F818/819 VOLTAGE-FREQUENCY GRAPH (INDUSTRIAL, EXTENDED)

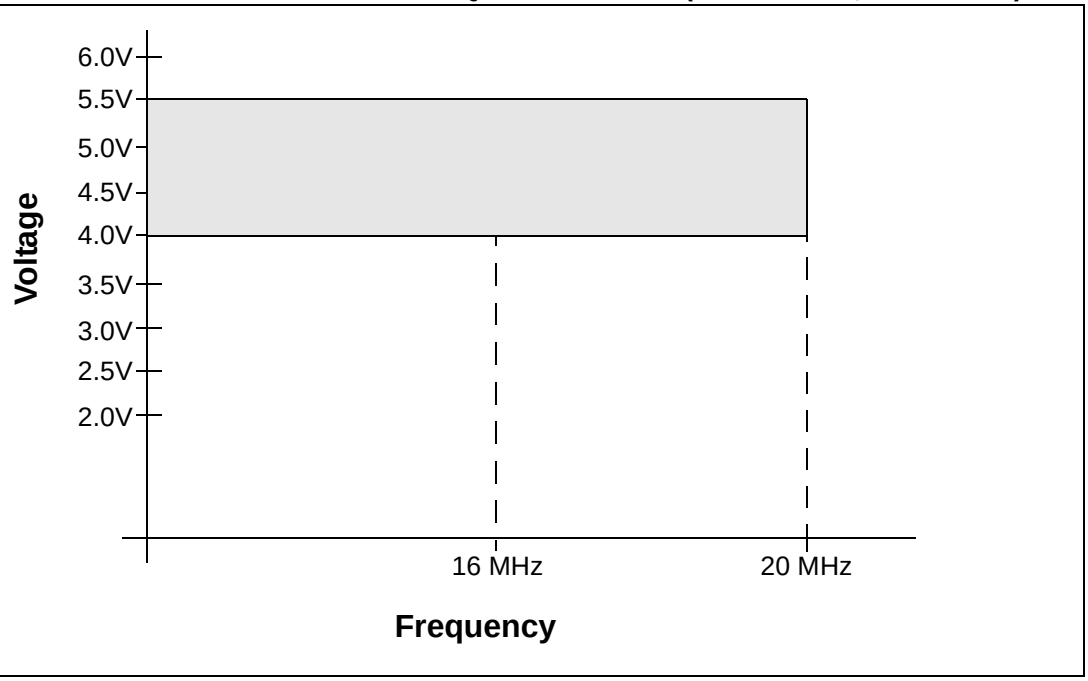
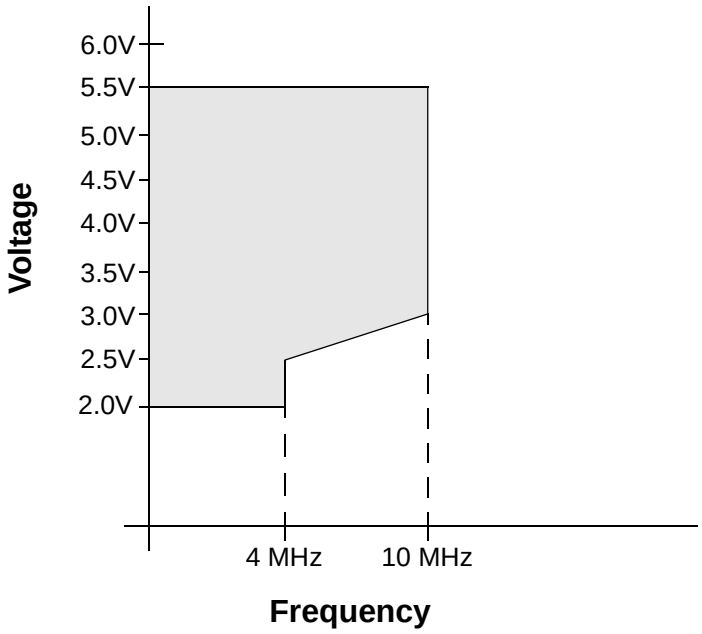


FIGURE 15-2: PIC16LF818/819 VOLTAGE-FREQUENCY GRAPH (INDUSTRIAL)



F_{MAX} = (12 MHz/V) ($V_{DDAPPMIN}$ – 2.5V) + 4 MHz

Note 1: $V_{DDAPPMIN}$ is the minimum voltage of the PIC® device in the application.

2: F_{MAX} has a maximum frequency of 10 MHz.

15.2 DC Characteristics: Power-Down and Supply Current PIC16F818/819 (Industrial, Extended) PIC16LF818/819 (Industrial)

PIC16LF818/819 (Industrial)		**Standard Operating Conditions (unless otherwise stated)** Operating temperature -40°C ≤ TA ≤ +85°C for industrial					
PIC16F818/819 (Industrial, Extended)		**Standard Operating Conditions (unless otherwise stated)** Operating temperature -40°C ≤ TA ≤ +85°C for industrial -40°C ≤ TA ≤ +125°C for extended					
Param No.	**Device**	**Typ**	**Max**	**Units**	**Conditions**		
	Power-Down Current (IPD)(1)						
	PIC16LF818/819	0.1	0.4	µA	-40°C	VDD = 2.0V	
		0.1	0.4	µA	+25°C		
		0.4	1.5	µA	+85°C		
	PIC16LF818/819	0.3	0.5	µA	-40°C	VDD = 3.0V	
		0.3	0.5	µA	+25°C		
		0.7	1.7	µA	+85°C		
	All devices	0.6	1.0	µA	-40°C	VDD = 5.0V	
		0.6	1.0	µA	+25°C		
		1.2	5.0	µA	+85°C		
	Extended devices	6.0	28	µA	+125°C		

Legend: Shading of rows is to assist in readability of the table.

Note 1: The power-down current in Sleep mode does not depend on the oscillator type. Power-down current is measured with the part in Sleep mode, with all I/O pins in high-impedance state and tied to VDD or VSS and all features that add delta current disabled (such as WDT, Timer1 Oscillator, BOR, etc.).

2: The supply current is mainly a function of operating voltage, frequency and mode. Other factors, such as I/O pin loading and switching rate, oscillator type and circuit, internal code execution pattern and temperature, also have an impact on the current consumption.
The test conditions for all IDD measurements in active operation mode are:
OSC1 = external square wave, from rail-to-rail; all I/O pins tri-stated, pulled to VDD;
MCLR = VDD; WDT enabled/disabled as specified.

3: For RC oscillator configurations, current through REXT is not included. The current through the resistor can be estimated by the formula Ir = VDD/2REXT (mA) with REXT in kΩ.

15.2 DC Characteristics: Power-Down and Supply Current PIC16F818/819 (Industrial, Extended) PIC16LF818/819 (Industrial) (Continued)

PIC16LF818/819 (Industrial)		**Standard Operating Conditions (unless otherwise stated)** Operating temperature -40°C ≤ TA ≤ +85°C for industrial					
PIC16F818/819 (Industrial, Extended)		**Standard Operating Conditions (unless otherwise stated)** Operating temperature -40°C ≤ TA ≤ +85°C for industrial -40°C ≤ TA ≤ +125°C for extended					
Param No.	**Device**	**Typ**	**Max**	**Units**	**Conditions**		
	Supply Current (IDD)(2,3)						
	PIC16LF818/819	9	20	µA	-40°C	VDD = 2.0V	FOSC = 32 kHz (LP Oscillator)
		7	15	µA	+25°C		
		7	15	µA	+85°C		
	PIC16LF818/819	16	30	µA	-40°C	VDD = 3.0V	
		14	25	µA	+25°C		
		14	25	µA	+85°C		
	All devices	32	40	µA	-40°C	VDD = 5.0V	
		26	35	µA	+25°C		
		26	35	µA	+85°C		
	Extended devices	35	53	µA	+125°C		

Legend: Shading of rows is to assist in readability of the table.

Note 1: The power-down current in Sleep mode does not depend on the oscillator type. Power-down current is measured with the part in Sleep mode, with all I/O pins in high-impedance state and tied to VDD or VSS and all features that add delta current disabled (such as WDT, Timer1 Oscillator, BOR, etc.).

2: The supply current is mainly a function of operating voltage, frequency and mode. Other factors, such as I/O pin loading and switching rate, oscillator type and circuit, internal code execution pattern and temperature, also have an impact on the current consumption.

The test conditions for all IDD measurements in active operation mode are:

OSC1 = external square wave, from rail-to-rail; all I/O pins tri-stated, pulled to VDD;

$\overline{MCLR}$ = VDD; WDT enabled/disabled as specified.

3: For RC oscillator configurations, current through REXT is not included. The current through the resistor can be estimated by the formula Ir = VDD/2REXT (mA) with REXT in kΩ.

15.2 DC Characteristics: Power-Down and Supply Current PIC16F818/819 (Industrial, Extended) PIC16LF818/819 (Industrial) (Continued)

PIC16LF818/819 (Industrial)		**Standard Operating Conditions (unless otherwise stated)** Operating temperature -40°C ≤ TA ≤ +85°C for industrial					
PIC16F818/819 (Industrial, Extended)		**Standard Operating Conditions (unless otherwise stated)** Operating temperature -40°C ≤ TA ≤ +85°C for industrial -40°C ≤ TA ≤ +125°C for extended					
Param No.	**Device**	**Typ**	**Max**	**Units**	**Conditions**		
D022 (ΔIWDT)	**Module Differential Currents (ΔIWDT, ΔIBOR, ΔILVD, ΔIOSCB, ΔIAD)**						
	Watchdog Timer	1.5	3.8	µA	-40°C	VDD = 2.0V	
		2.2	3.8	µA	+25°C		
		2.7	4.0	µA	+85°C		
		2.3	4.6	µA	-40°C	VDD = 3.0V	
		2.7	4.6	µA	+25°C		
		3.1	4.8	µA	+85°C		
		3.0	10.0	µA	-40°C	VDD = 5.0V	
		3.3	10.0	µA	+25°C		
		3.9	13.0	µA	+85°C		
	Extended Devices	5.0	21.0	µA	+125°C		
D022A (ΔIBOR)	**Brown-out Reset**	40	60	µA	-40°C to +85°C	VDD = 5.0V	
D025 (ΔIOSCB)	**Timer1 Oscillator**	1.7	2.3	µA	-40°C	VDD = 2.0V	32 kHz on Timer1
		1.8	2.3	µA	+25°C		
		2.0	2.3	µA	+85°C		
		2.2	3.8	µA	-40°C	VDD = 3.0V	
		2.6	3.8	µA	+25°C		
		2.9	3.8	µA	+85°C		
		3.0	6.0	µA	-40°C	VDD = 5.0V	
		3.2	6.0	µA	+25°C		
		3.4	7.0	µA	+85°C		
D026 (ΔIAD)	**A/D Converter**	0.001	2.0	µA	-40°C to +85°C	VDD = 2.0V	A/D on, Sleep, not converting
		0.001	2.0	µA	-40°C to +85°C	VDD = 3.0V	
		0.003	2.0	µA	-40°C to +85°C	VDD = 5.0V	
	Extended Devices	4.0	8.0	µA	-40°C to +125°C		

Legend: Shading of rows is to assist in readability of the table.

Note 1: The power-down current in Sleep mode does not depend on the oscillator type. Power-down current is measured with the part in Sleep mode, with all I/O pins in high-impedance state and tied to VDD or VSS and all features that add delta current disabled (such as WDT, Timer1 Oscillator, BOR, etc.).

2: The supply current is mainly a function of operating voltage, frequency and mode. Other factors, such as I/O pin loading and switching rate, oscillator type and circuit, internal code execution pattern and temperature, also have an impact on the current consumption.

The test conditions for all IDD measurements in active operation mode are:

OSC1 = external square wave, from rail-to-rail; all I/O pins tri-stated, pulled to VDD;
MCLR = VDD; WDT enabled/disabled as specified.

3: For RC oscillator configurations, current through REXT is not included. The current through the resistor can be estimated by the formula Ir = VDD/2REXT (mA) with REXT in kΩ.

15.5 Timing Parameter Symbology

The timing parameter symbols have been created using one of the following formats:

1. TppS2ppS
2. TppS
3. TCC:ST (I²C specifications only)
4. Ts (I²C specifications only)

T			
F	Frequency	T	Time

Lowercase letters (pp) and their meanings:

pp			
cc	CCP1	osc	OSC1
ck	CLKO	rd	$\overline{RD}$
cs	$\overline{CS}$	rw	$\overline{RD}$ or $\overline{WR}$
di	SDI	sc	SCK
do	SDO	ss	$\overline{SS}$
dt	Data in	t0	T0CKI
io	I/O port	t1	T1CKI
mc	$\overline{MCLR}$	wr	$\overline{WR}$

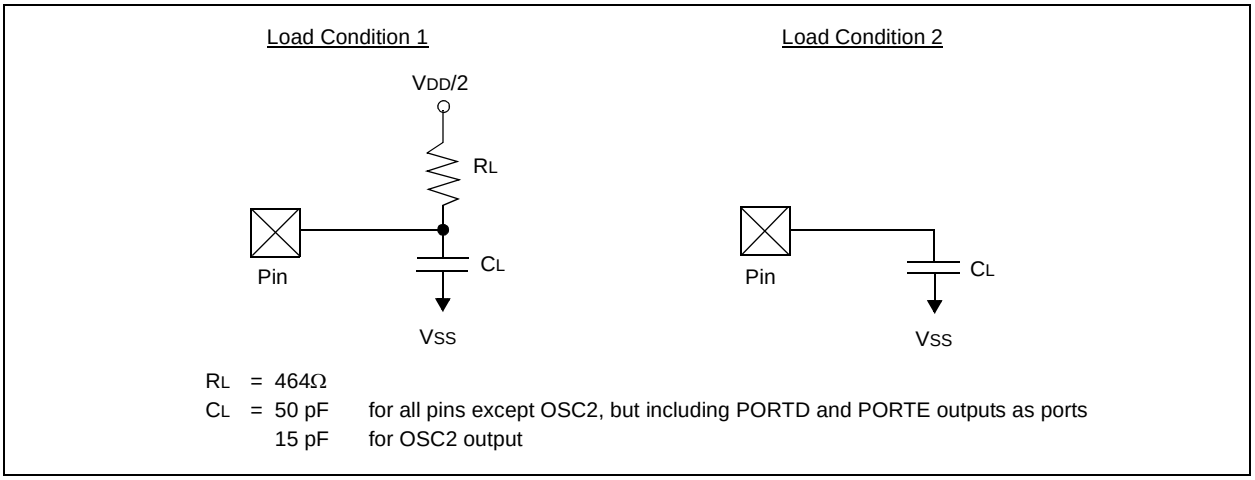
Uppercase letters and their meanings:

S			
F	Fall	P	Period
H	High	R	Rise
I	Invalid (High-impedance)	V	Valid
L	Low	Z	High-impedance
I²C only			
AA	output access	High	High
BUF	Bus free	Low	Low

TCC:ST (I²C specifications only)

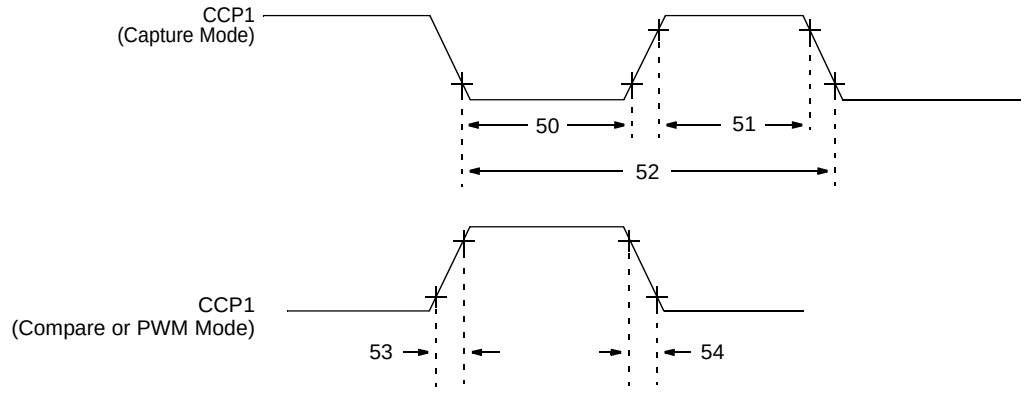
CC			
HD	Hold	SU	Setup
ST			
DAT	DATA input hold	STO	Stop condition
STA	Start condition		

FIGURE 15-3: LOAD CONDITIONS



RL = 464Ω
CL = 50 pF for all pins except OSC2, but including PORTD and PORTE outputs as ports
15 pF for OSC2 output

FIGURE 15-9: CAPTURE/COMPARE/PWM TIMINGS (CCP1)



Note: Refer to Figure 15-3 for load conditions.

TABLE 15-5: CAPTURE/COMPARE/PWM REQUIREMENTS (CCP1)

Param No.	Symbol	Characteristic			Min	Typ†	Max	Units	Conditions
50*	TccL	CCP1 Input Low Time	No Prescaler		0.5 TCY + 20	—	—	ns	
			With Prescaler	PIC16**F**818/819	10	—	—	ns	
				PIC16**LF**818/819	20	—	—	ns	
51*	TccH	CCP1 Input High Time	No Prescaler		0.5 TCY + 20	—	—	ns	
			With Prescaler	PIC16**F**818/819	10	—	—	ns	
				PIC16**LF**818/819	20	—	—	ns	
52*	TccP	CCP1 Input Period			$\frac{3\ T_{CY} + 40}{N}$	—	—	ns	N = prescale value (1,4 or 16)
53*	TccR	CCP1 Output Rise Time		PIC16**F**818/819	—	10	25	ns	
				PIC16**LF**818/819	—	25	50	ns	
54*	TccF	CCP1 Output Fall Time		PIC16**F**818/819	—	10	25	ns	
				PIC16**LF**818/819	—	25	45	ns	

* These parameters are characterized but not tested.

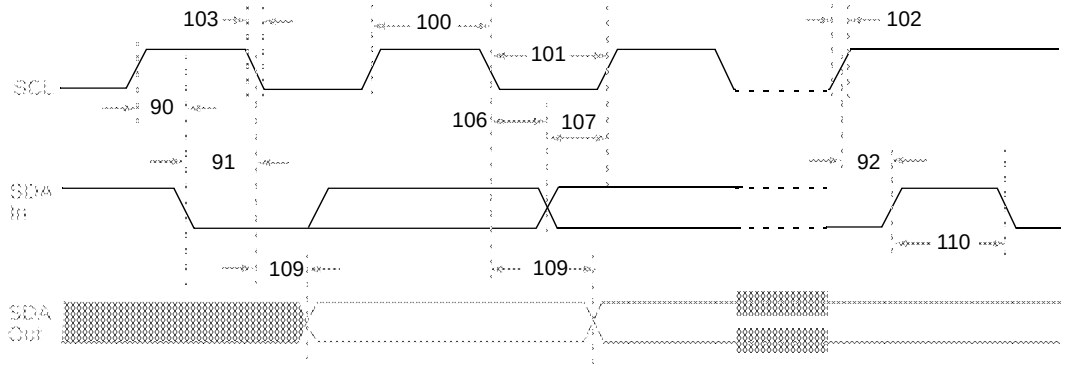
† Data in “Typ” column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

TABLE 15-7: I²C™ BUS START/STOP BITS REQUIREMENTS

Param No.	Symbol	Characteristic		Min	Typ	Max	Units	Conditions
90*	TSU:STA	Start Condition Setup Time	100 kHz mode	4700	—	—	ns	Only relevant for Repeated Start condition
			400 kHz mode	600	—	—		
91*	THD:STA	Start Condition Hold Time	100 kHz mode	4000	—	—	ns	After this period, the first clock pulse is generated
			400 kHz mode	600	—	—		
92*	TSU:STO	Stop Condition Setup Time	100 kHz mode	4700	—	—	ns	
			400 kHz mode	600	—	—		
93	THD:STO	Stop Condition Hold Time	100 kHz mode	4000	—	—	ns	
			400 kHz mode	600	—	—		

* These parameters are characterized but not tested.

FIGURE 15-15: I²C™ BUS DATA TIMING



Note: Refer to Figure 15-3 for load conditions.

16.0 DC AND AC CHARACTERISTICS GRAPHS AND TABLES

Note:	The graphs and tables provided following this note are a statistical summary based on a limited number of samples and are provided for informational purposes only. The performance characteristics listed herein are not tested or guaranteed. In some graphs or tables, the data presented may be outside the specified operating range (e.g., outside specified power supply range) and therefore, outside the warranted range.

"Typical" represents the mean of the distribution at 25°C. "Maximum" or "minimum" represents (mean + 3σ) or (mean – 3σ) respectively, where σ is a standard deviation, over the whole temperature range.

FIGURE 16-1: TYPICAL IDD vs. FOSC OVER VDD (HS MODE)

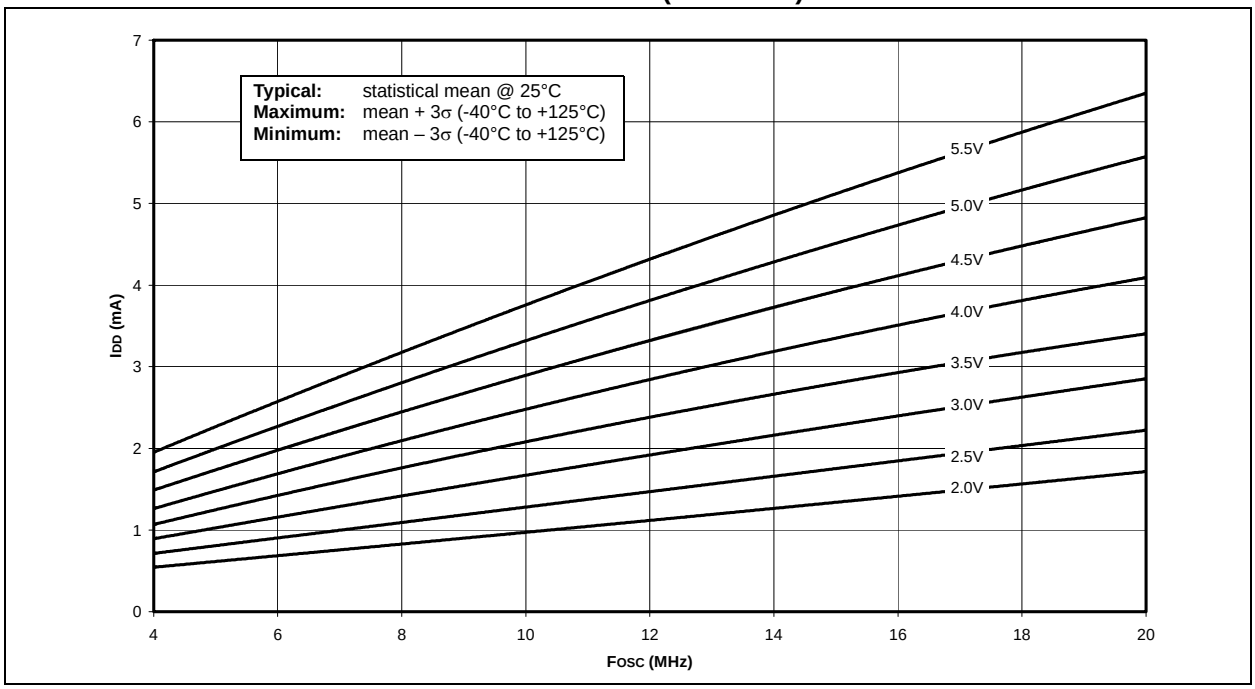


FIGURE 16-2: MAXIMUM IDD vs. FOSC OVER VDD (HS MODE)

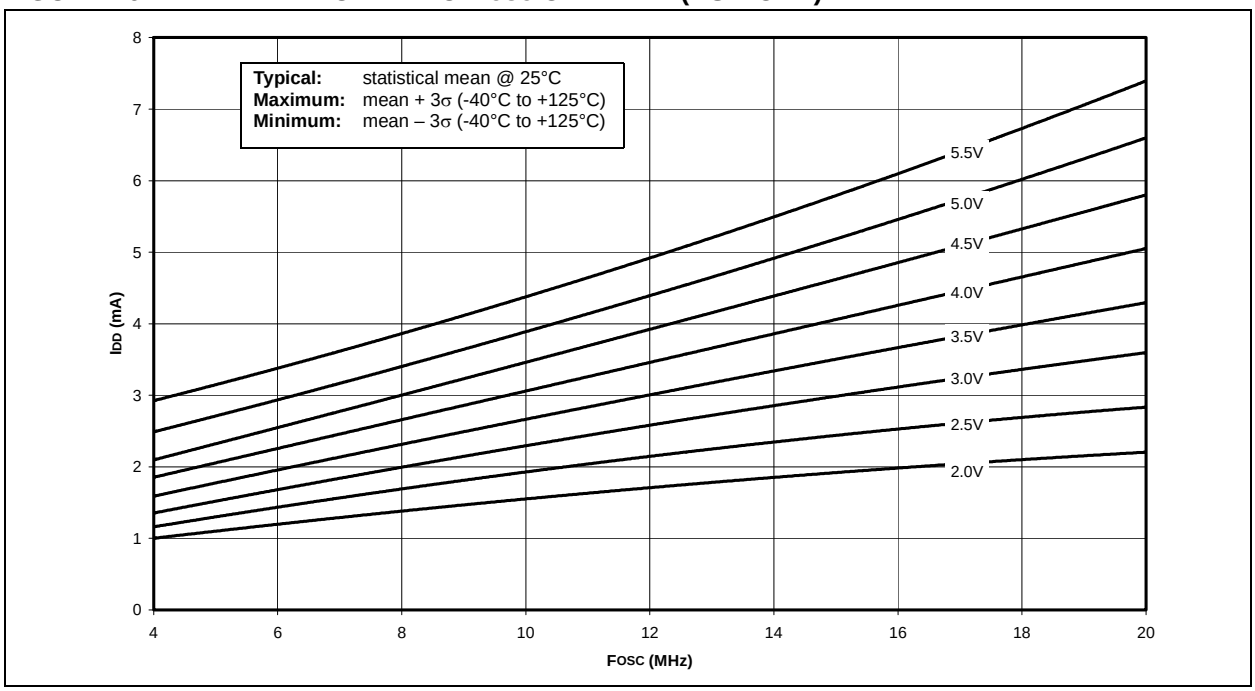


FIGURE 16-21: MINIMUM AND MAXIMUM VIN vs. VDD (TTL INPUT, -40°C TO +125°C)

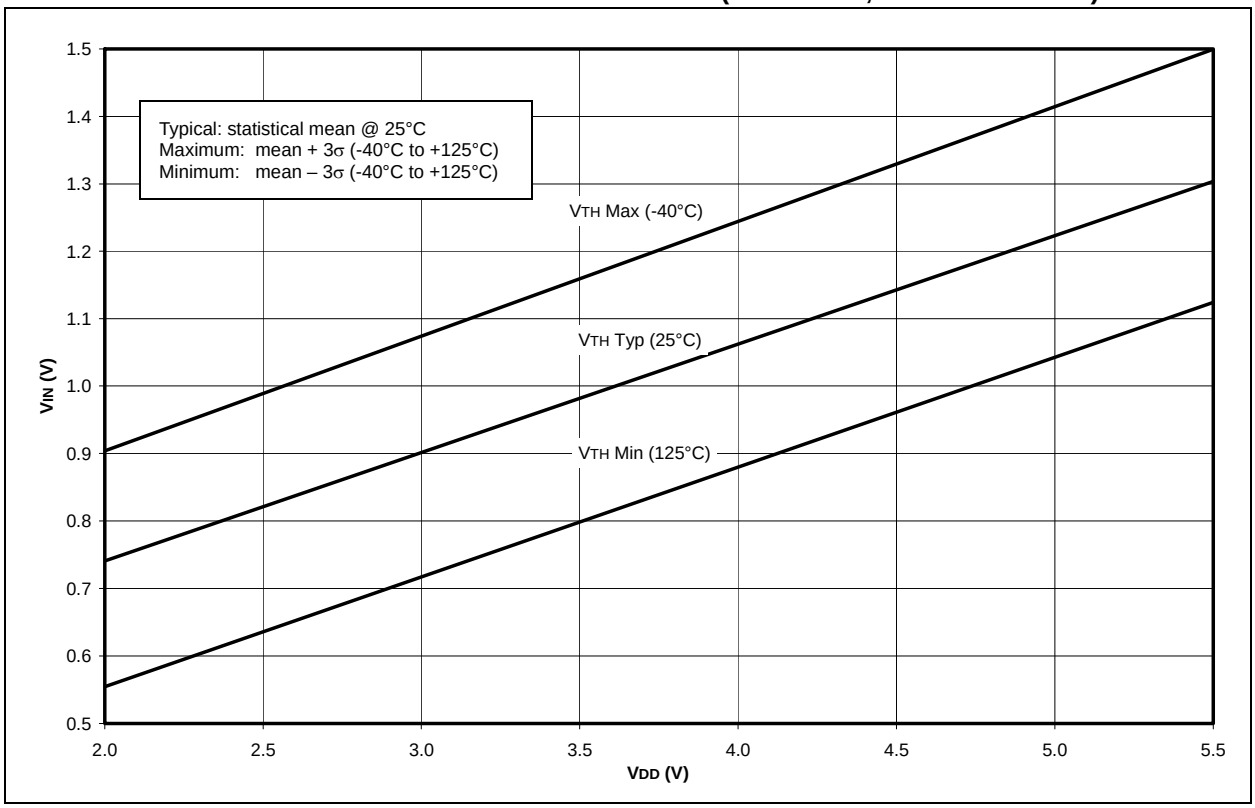
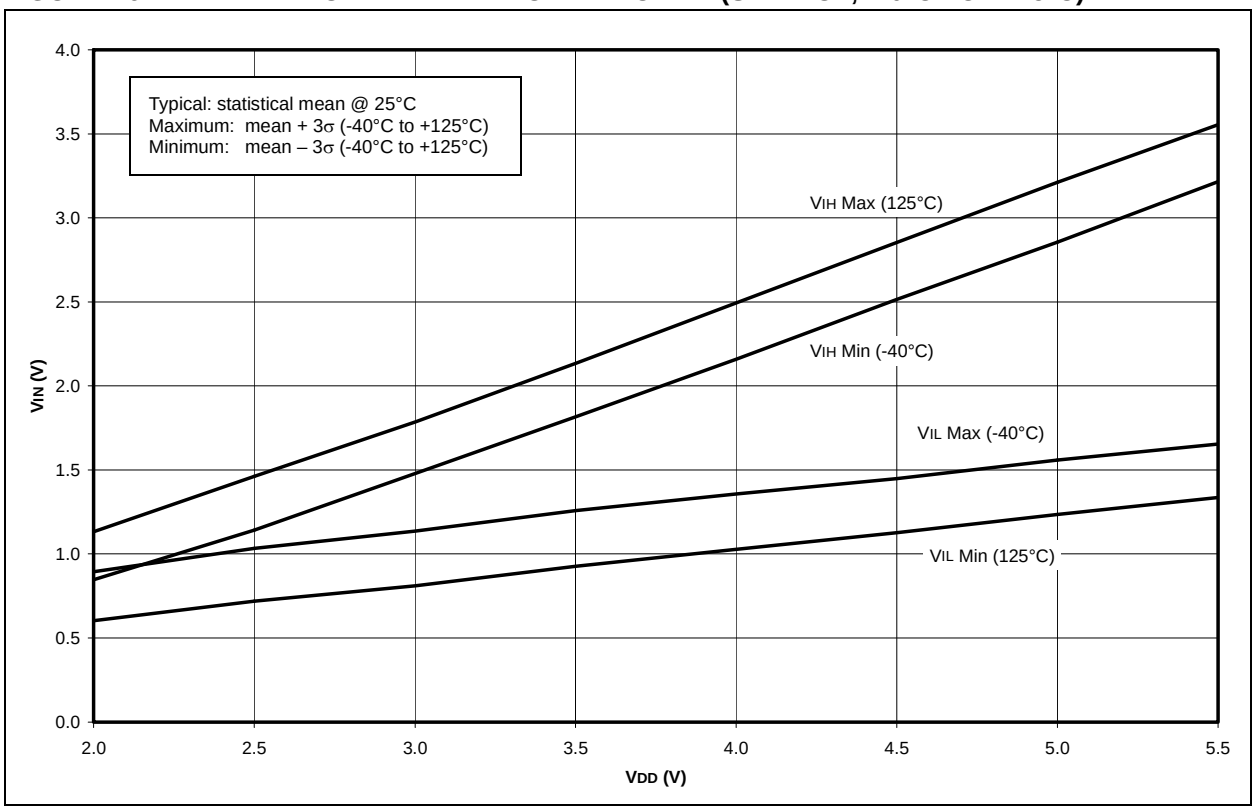


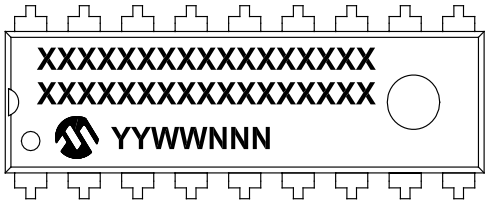
FIGURE 16-22: MINIMUM AND MAXIMUM VIN vs. VDD (ST INPUT, -40°C TO +125°C)



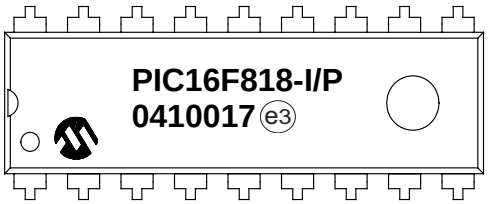
17.0 PACKAGING INFORMATION

17.1 Package Marking Information

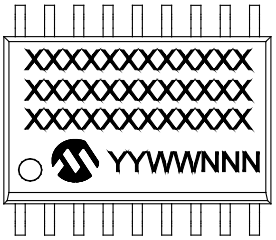
18-Lead PDIP (300 mil)



Example

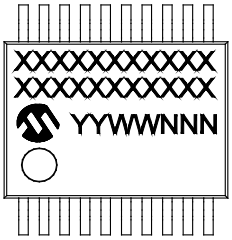


18-Lead SOIC (7.50 mm)

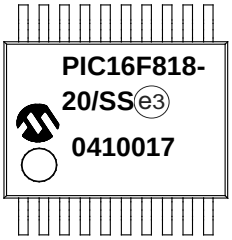


Example

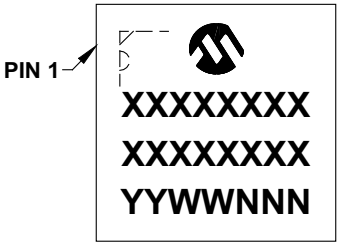
20-Lead SSOP (5.30 mm)



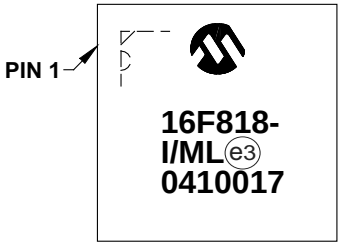
Example



28-Lead QFN (6x6 mm)



Example

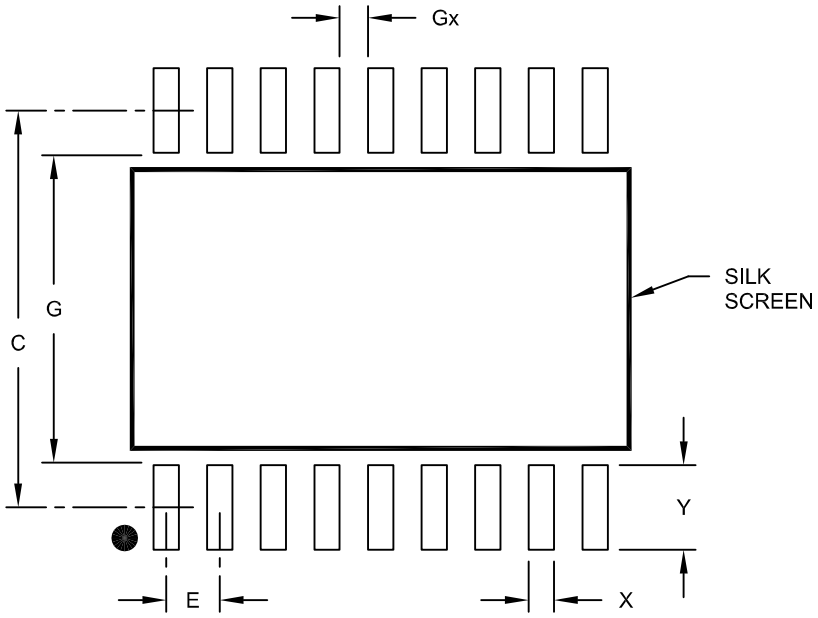


Legend:	XX...X	Customer-specific information
	Y	Year code (last digit of calendar year)
	YY	Year code (last 2 digits of calendar year)
	WW	Week code (week of January 1 is week ‘01’)
	NNN	Alphanumeric traceability code
	(e3)	Pb-free JEDEC designator for Matte Tin (Sn)
	*	This package is Pb-free. The Pb-free JEDEC designator ((e3)) can be found on the outer packaging for this package.

Note: In the event the full Microchip part number cannot be marked on one line, it will be carried over to the next line, thus limiting the number of available characters for customer-specific information.

18-Lead Plastic Small Outline (SO) - Wide, 7.50 mm Body [SOIC]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



RECOMMENDED LAND PATTERN

Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Contact Pitch	E		1.27 BSC	
Contact Pad Spacing	C		9.40	
Contact Pad Width	X			0.60
Contact Pad Length	Y			2.00
Distance Between Pads	Gx	0.67		
Distance Between Pads	G	7.40		

Notes:

1. Dimensioning and tolerancing per ASME Y14.5M

BSC: Basic Dimension. Theoretically exact value shown without tolerances.

Microchip Technology Drawing No. C04-2051A